

Power dissipation and hit efficiency of CNM 3D pixel sensors irradiated to $1.6e16 \text{ neq/cm}^2$

23-06-2022

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ATLAS - ITk

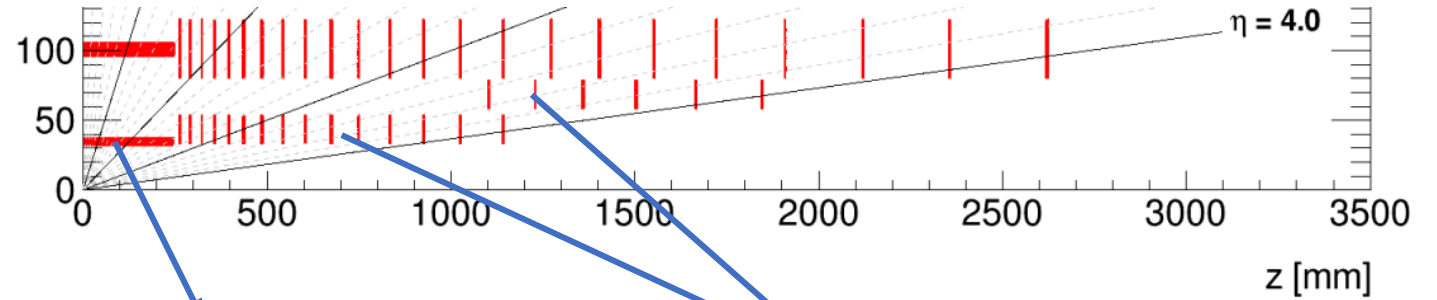
The Large Hadron Collider (LHC) will be upgraded to be able to reach about seven times its current nominal instantaneous luminosity.

The expected particle fluence will be $1.7e16 \text{ neq/cm}^2$ in the innermost layer.

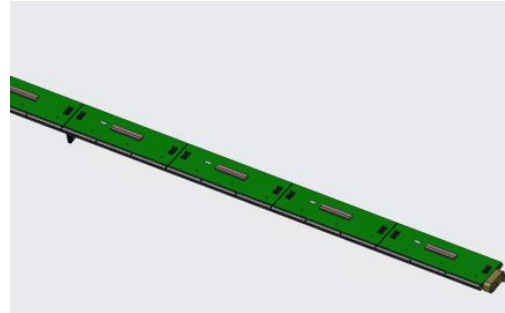
3D pixel sensors have been chosen for the innermost pixel layer of Inner Tracker (ITk) because of their high-radiation tolerance.

3D pixel silicon sensors in the ITk:

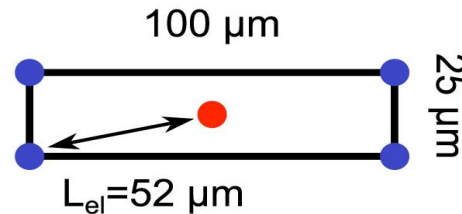
- Barrel: pixel cell $25 \times 100 \text{ }\mu\text{m}^2$ 1E
- Rings: pixel cell $50 \times 50 \text{ }\mu\text{m}^2$ 1E



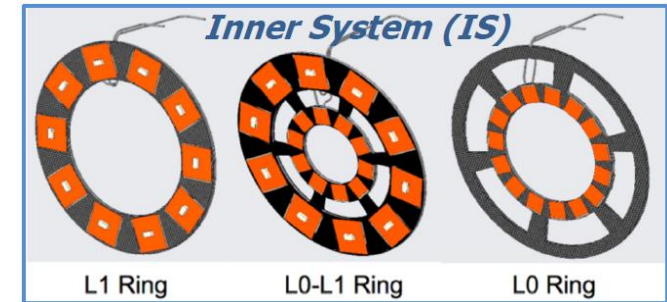
Barrel - staves



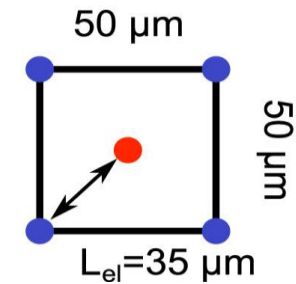
$25 \times 100 \text{ }\mu\text{m}^2$, 1E



Ring



$50 \times 50 \text{ }\mu\text{m}^2$, 1E



RD53A run at CNM

First 3D pixel sensor compatible with the RD53A chip manufactured at CNM.

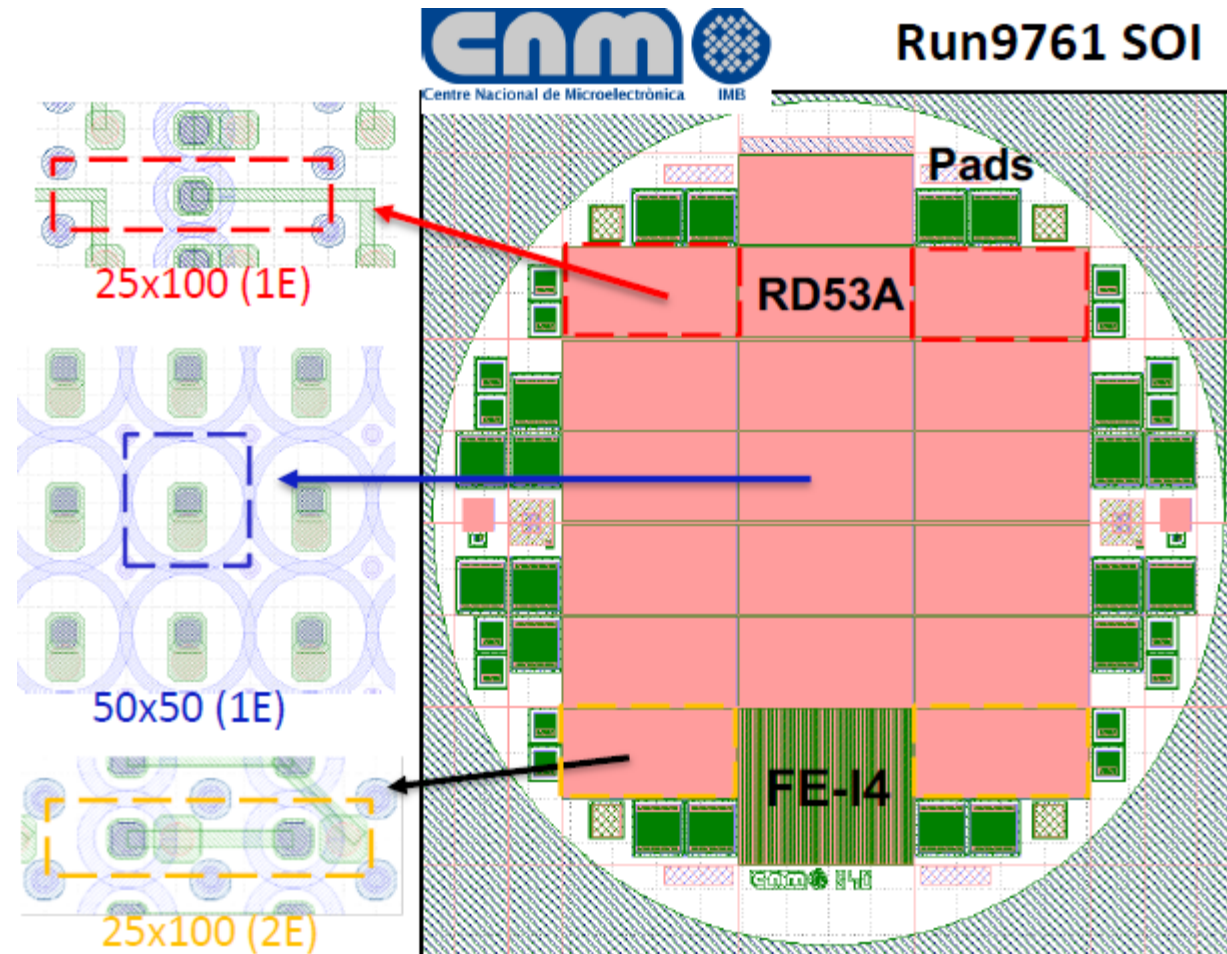
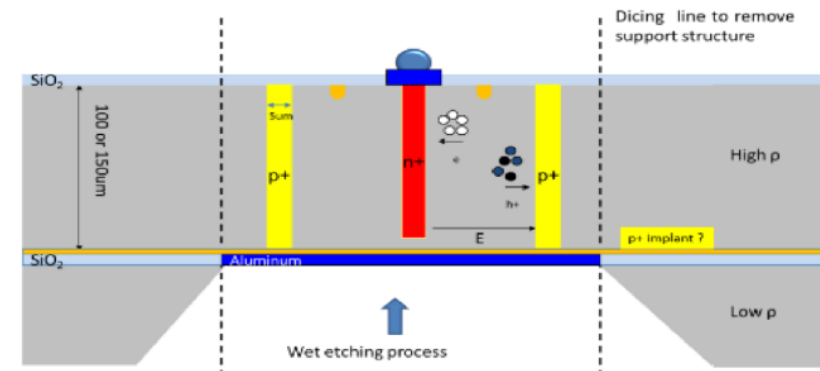
- Single sided process
 - Both p- and n-columns etched from the front
 - p-stop insulation
- Silicon on Insulator (SOI) wafers 150 μm active thickness with 300 μm handle wafer

The mask includes:

- 14x RD53A 50x50 μm^2 1E
- 2x RD53A 25x100 μm^2 1E
- 2x RD53A 25x100 μm^2 2E
- 1x FE-I4 50x50 μm^2 1E
- Pad diodes of 50x50 μm^2
- Pad diodes 25x100 μm^2

Sensors tested in this presentation are:

- 50x50 μm^2 1E pixels
- 25x100 μm^2 1E pixels.



RD53A module

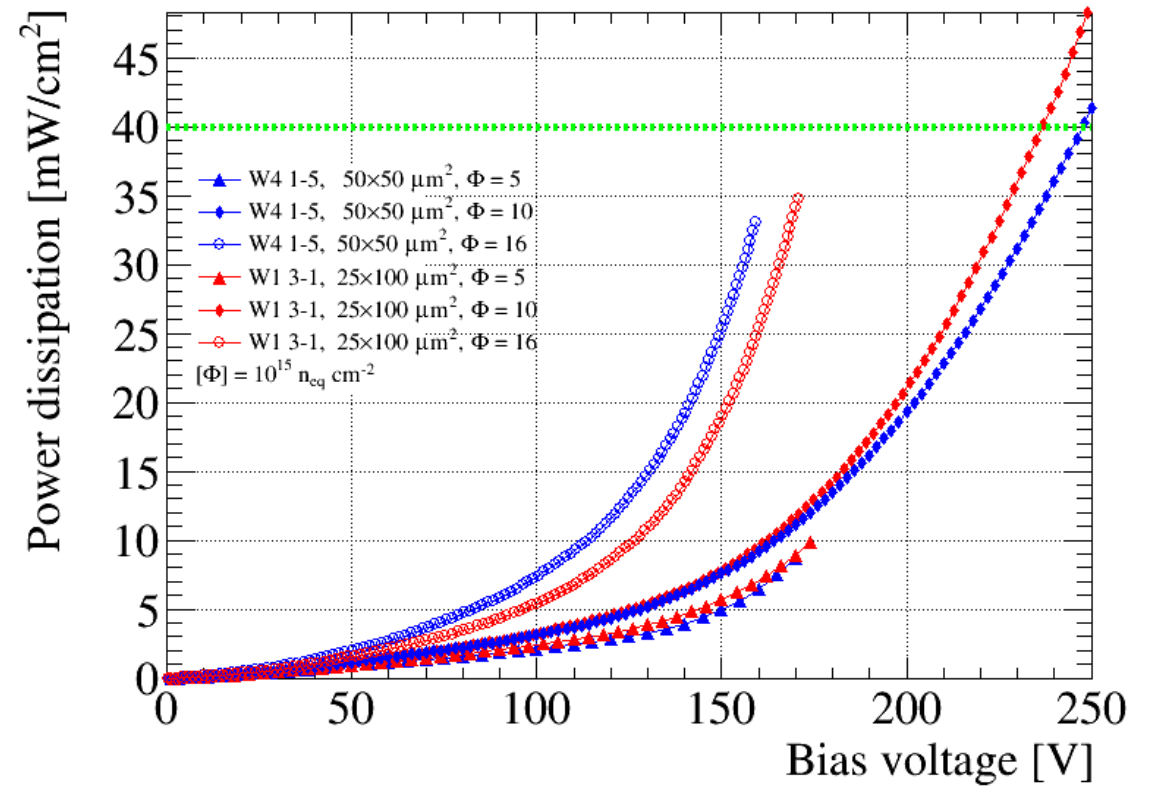
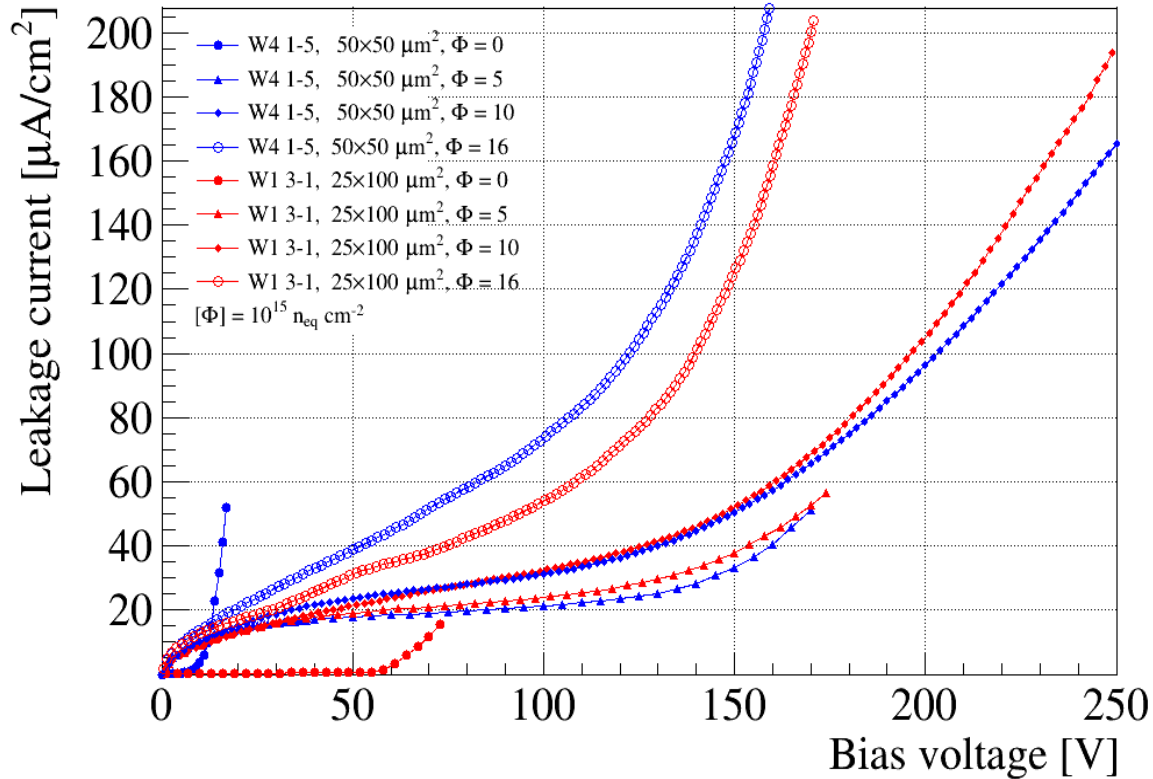
- Under-Bump Metallization (UBM) were performed at CNM.
- Flip-chip was carried out at IFAE.
- 50x50 was fully connected while the 25x100 had large disconnected areas on the right and left sides
- Both sensors were uniformly irradiated with proton beams in different facilities up to 1.6×10^{16} neq/cm²:



Sensor name	W4 1-5	W1 3-1
Pitch [μm^2]	50×50	25×100
First irradiation step		
Facility	KIT	KIT
Φ [$\text{n}_{\text{eq}}/\text{cm}^2$]	5.0×10^{15}	5.1×10^{15}
TID [Mrad]	750	750
Second irradiation step		
Facility	CYRIC	BU
Φ [$\text{n}_{\text{eq}}/\text{cm}^2$]	4.8×10^{15}	5.0×10^{15}
TID [Mrad]	350	665
Third irradiation step		
Facility	CYRIC	CYRIC
Φ [$\text{n}_{\text{eq}}/\text{cm}^2$]	6×10^{15}	6×10^{15}
TID [Mrad]	420	420
Total		
Φ [$\text{n}_{\text{eq}}/\text{cm}^2$]	1.6×10^{16}	1.6×10^{16}
TID [Mrad]	1520	1835

Table shows the Total Ionization Dose (TID) and the particle fluence at different radiation steps.

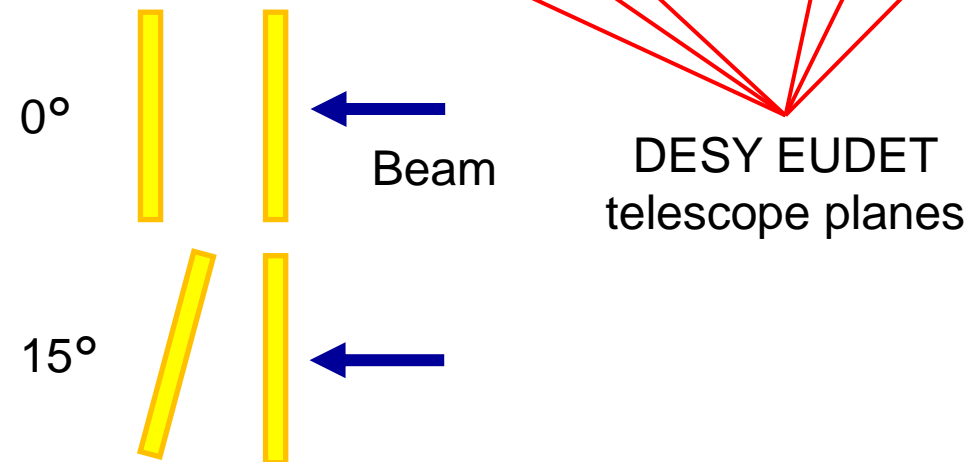
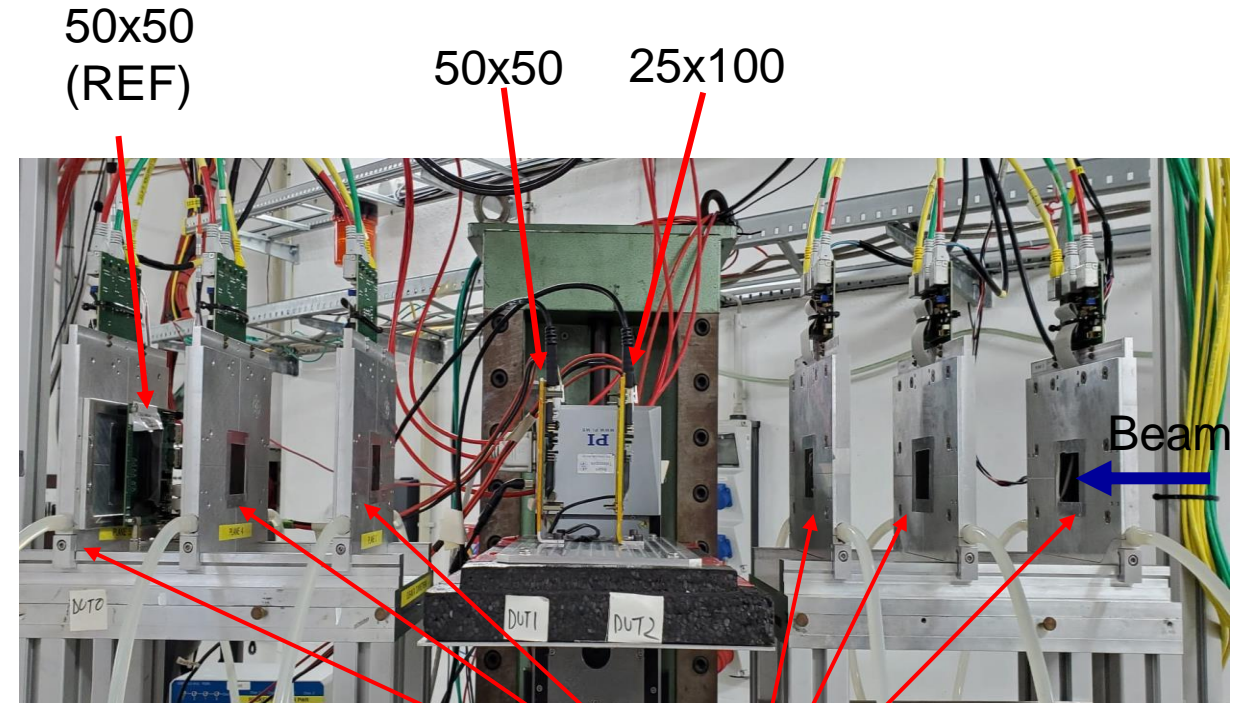
Sensor IV - Power dissipation



- Irradiated modules were measured at -25° in a climate chamber.
- Not irradiated modules were measured at room temperature.
- For ATLAS specifications, the Power Dissipation must be lower than $40 \text{ mW}/\text{cm}^2$.
- After irradiation to $1.6 \times 10^{16} \text{ neq}/\text{cm}^2$. These sensors can be operated up to 160V.

DESY setup – December 2021

- EUDET telescope: 6 MIMOSA pixel detectors for tracking.
- We use a 50x50 non-irradiated RD53A planar sensor as timing reference.
- We use dry ice to reduce the leakage current on the modules.
 - Box temperature: -48°C
- We used EUTELESCOPE to reconstruct the particle tracks and TBMon2 to calculate the efficiency.
- 50x50 was measured at 0° (normal to the incident beam direction) and at 15°
- 25x100 was measured only at 0° .



Threshold scan after tuning

The RD53A chip prototype chip is made of 3 different analog FE parts.

The Lin FE was very noisy and could not be tuned, we measured only the Diff FE (selected for the final ALTAS ITkPix chip)

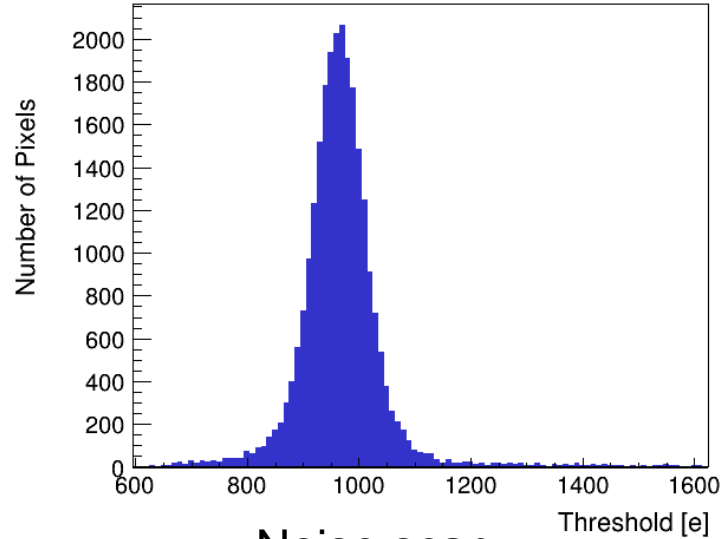
50x50:

- Threshold value around 1000 e.
- The noise is lower than 100 e.

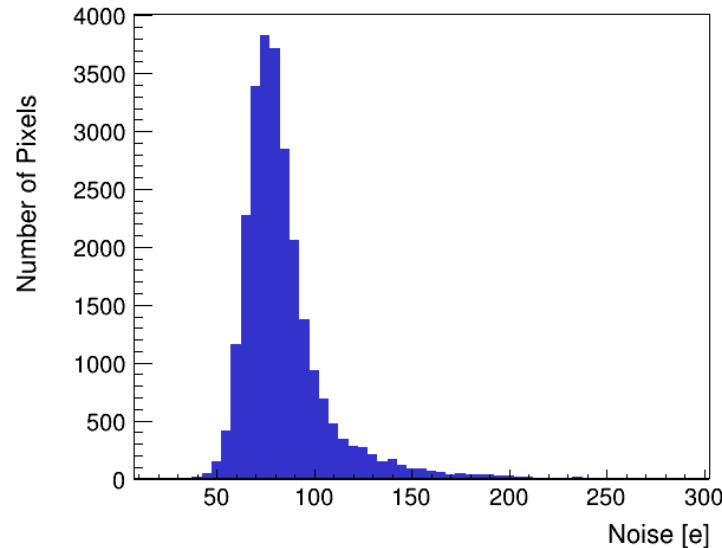
25x100

- Threshold value around 1300 e.
- Large threshold range and tail.
- Two noise distributions for connected (around 300e) and disconnected (200e) pixels.

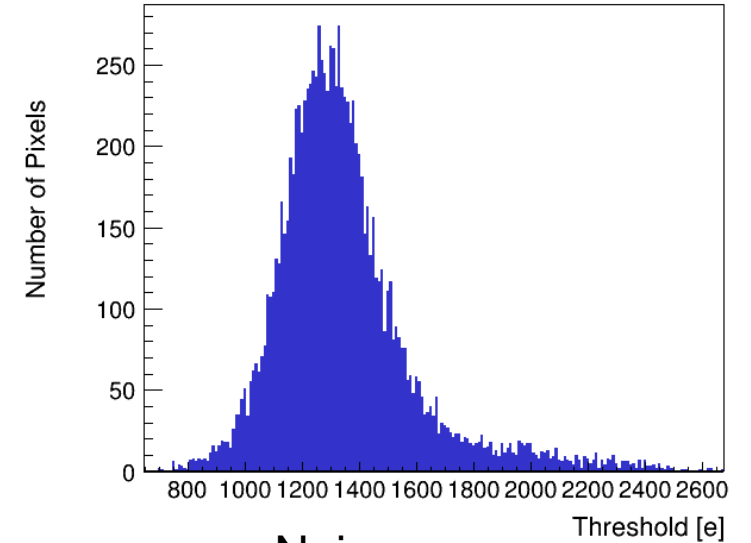
Threshold scan 50x50



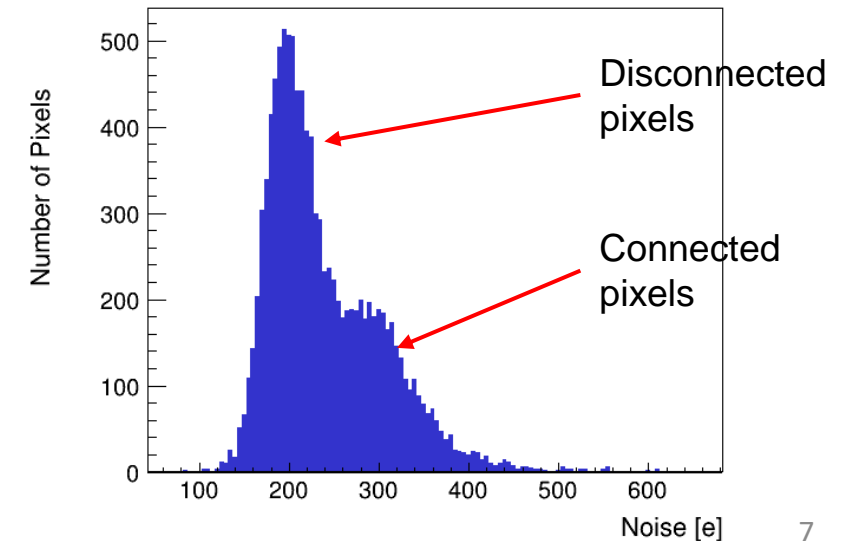
Noise scan



Threshold scan 25x100



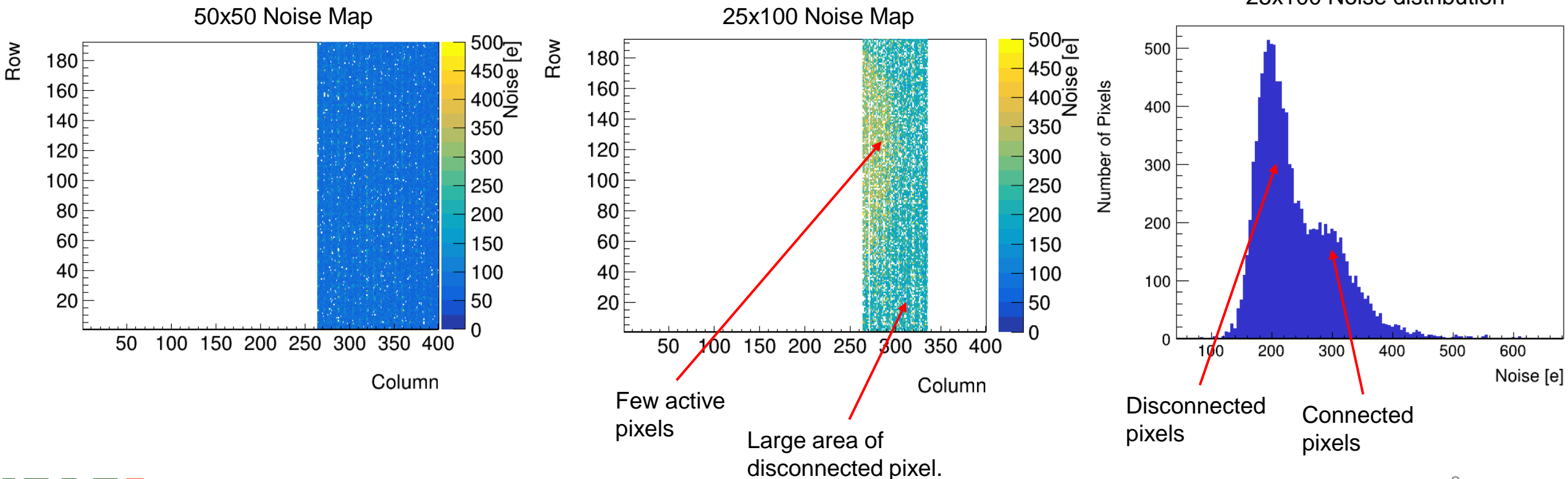
Noise scan



25x100 1E – disconnected areas

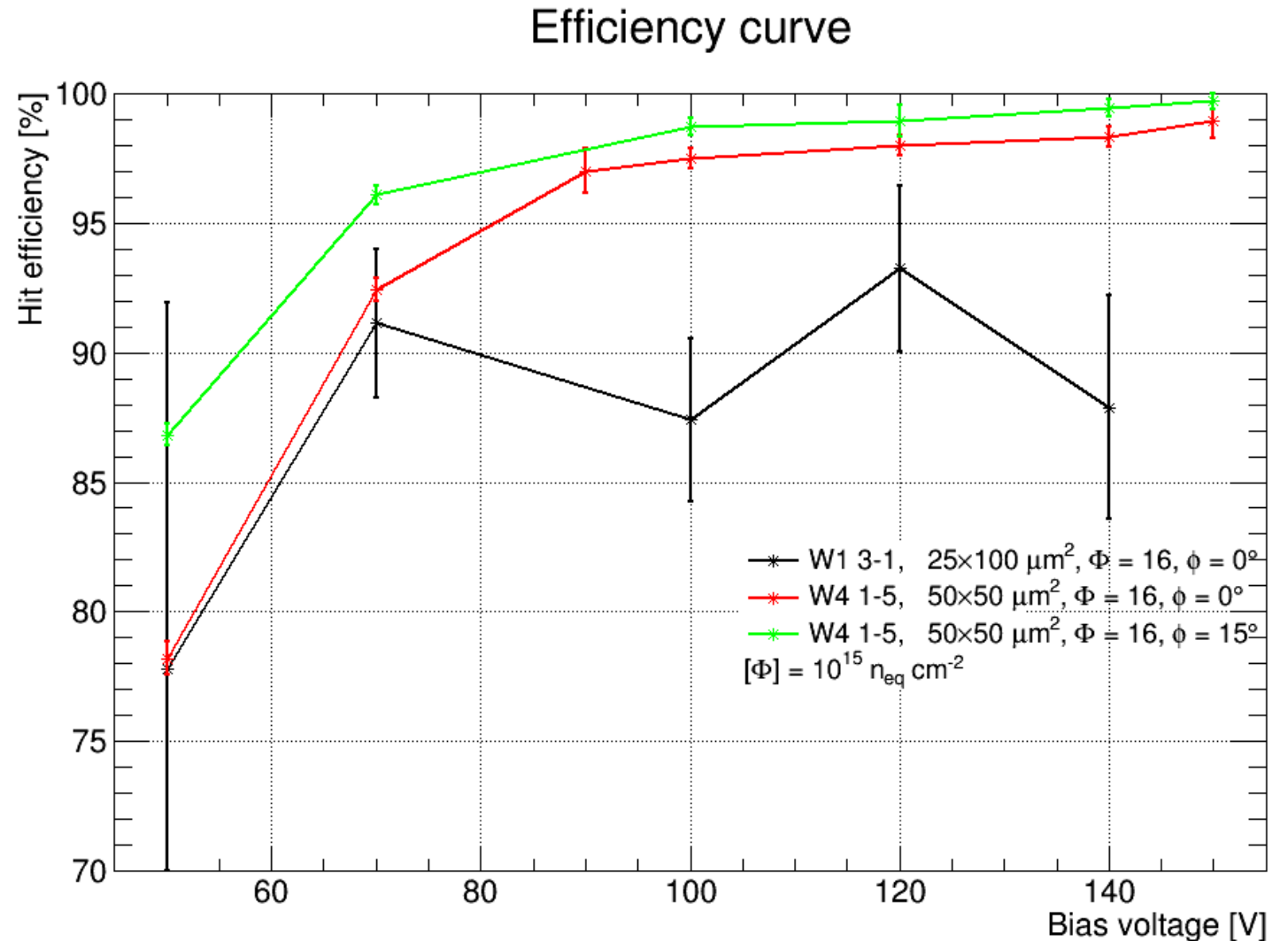
The noise scan of the 25x100 shows different noise distributions for the connected and disconnected pixels.

- 1k noise pixels were masked in the 25x100 around the active area (19%).
- 62 noise pixels were masked in the 50x50 in the diffFE (0.25%)



Efficiency vs bias voltage plot

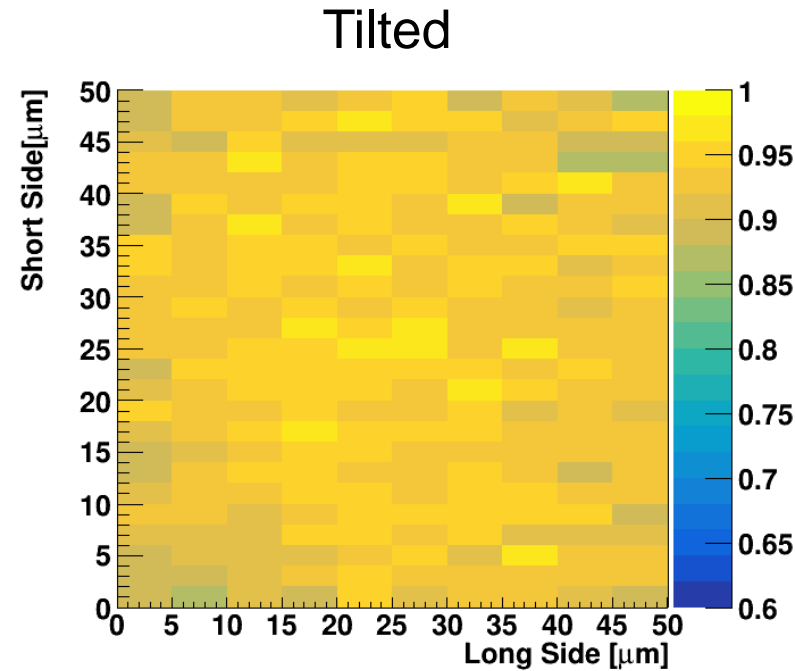
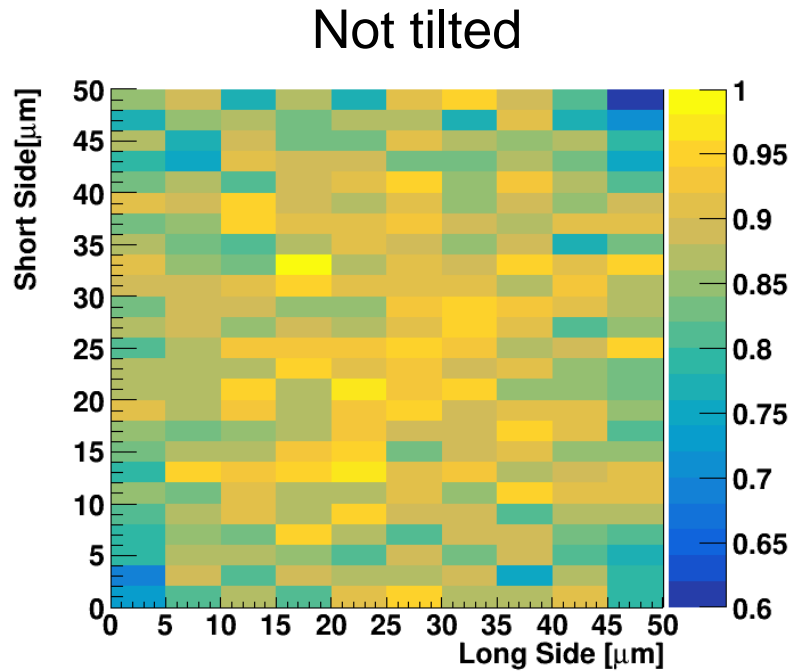
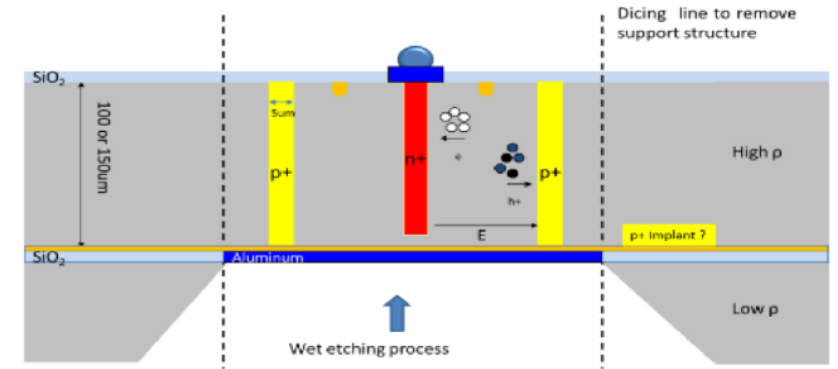
- Tilted 50x50 (green curve) reach an efficiency higher than 97% at 80V.
- At 100V, the 50x50 (red curve) reach an efficiency higher than 97%.
- 25x100 efficiency oscillates around 90%.
 - Very low statistic (large disconnected area and very few pixels analyzed)
 - Larger Total Ionization Dose (TID) and more noise in the front-end
 - Larger threshold (and tails)



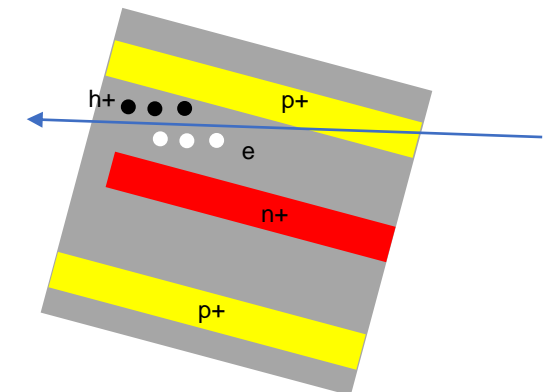
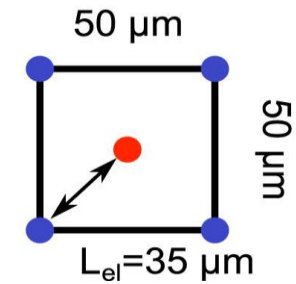
Efficiency pixel map 50x50 at 70V

Efficiency pixel map for the same sensor (50x50) normal (left) and tilted 15° (right) at the same scale.

Efficiency in the corners for the tilted one is higher and uniform.



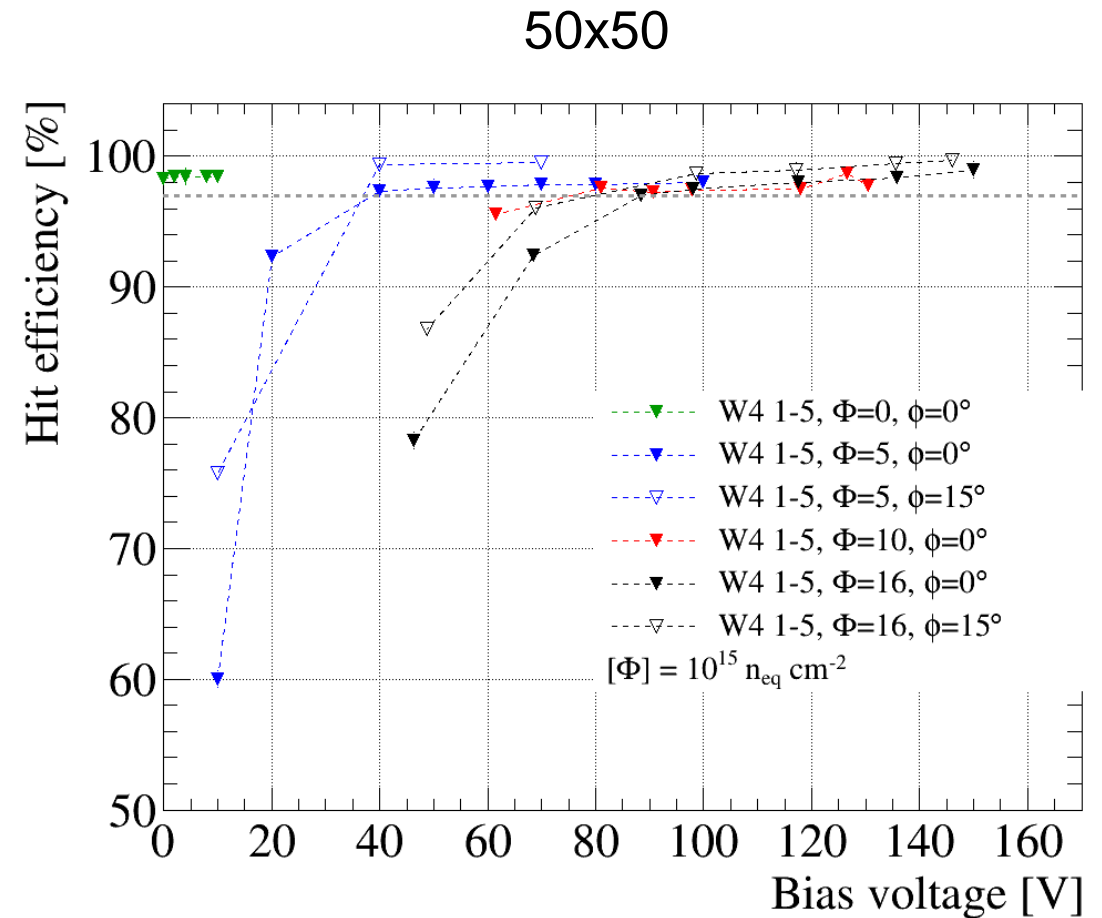
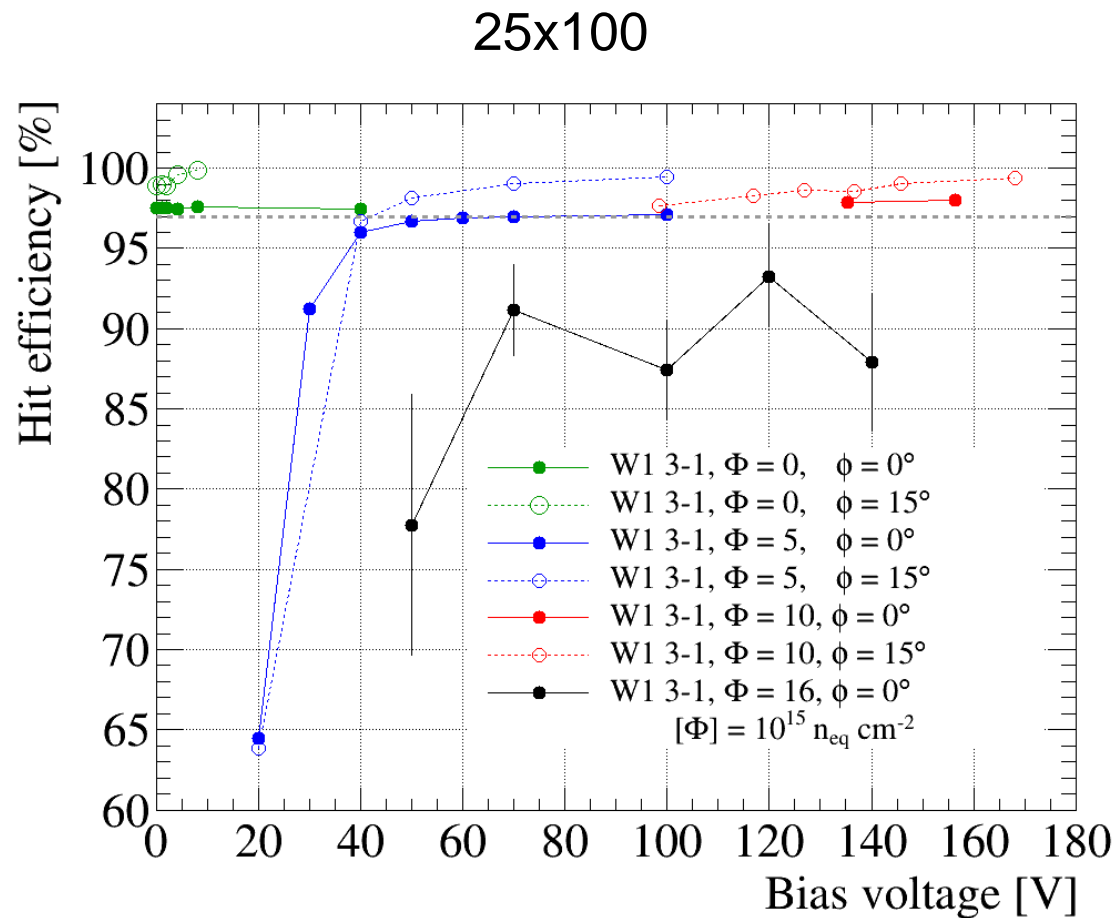
50×50 μm², 1E



15° tilted scheme

Efficiency vs bias voltage plot

Overview of the hit efficiency after each irradiation step.



Conclusion

I presented efficiency results of two 3D irradiated pixel sensors, 25x100 and 50x50, both irradiated to 1.6×10^{16} neq/cm².

- The 50x50 not-tilted reaches 97% efficiency with just 100 V.
- The 50x50 tilted 15° reaches 97% efficiency at 80 V.
- 25x100 sensor presents a large disconnected area and a large noise in the chip. Efficiency oscillated around 90%.

The power dissipation of both sensor is below 40 mW/cm² up to 160 V.

- Power dissipation for the 50x50 is around 7 mW/cm² at 100 V, when it reaches the 97% hit efficiency.
- Power dissipation for the 25x100 is around 5 mW/cm² at 90 V, when it reaches the 90% hit efficiency.

Outlook

New Silicon-on-Silicon (SiSi) 25x100 1E device already mounted on a pcb for future tests.

Two SiSi modules have been irradiated at Fermilab, waiting for cooling down.

New SiSi pre-production at CNM in progress and expected for December.

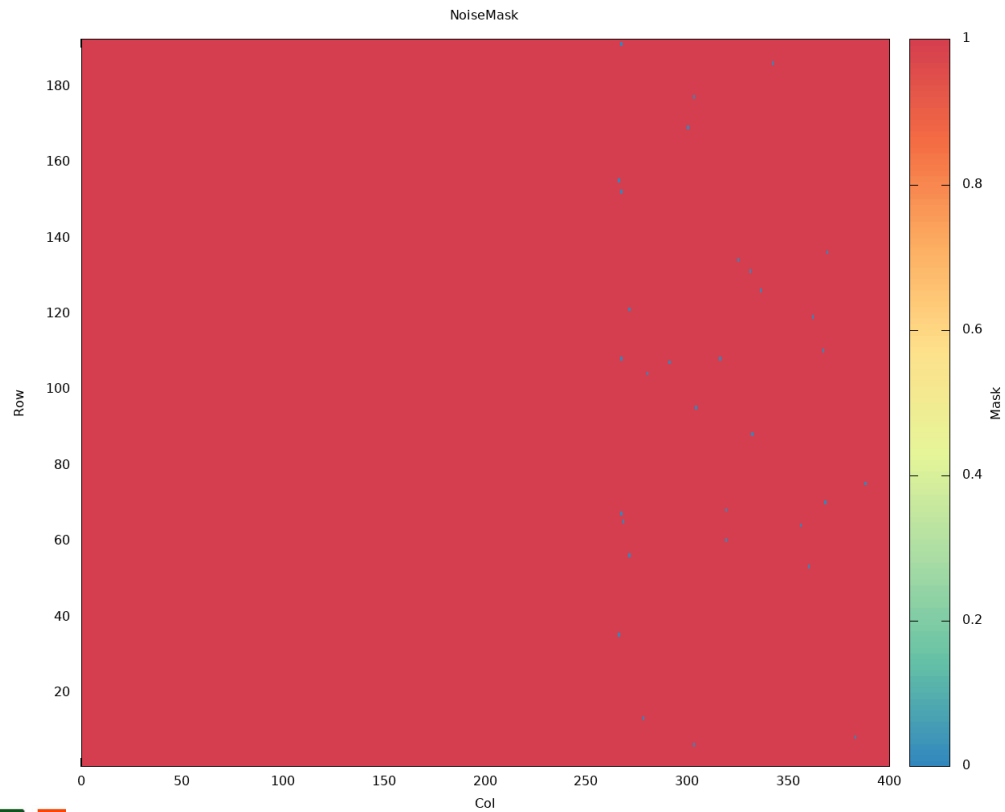
Thanks for your attention



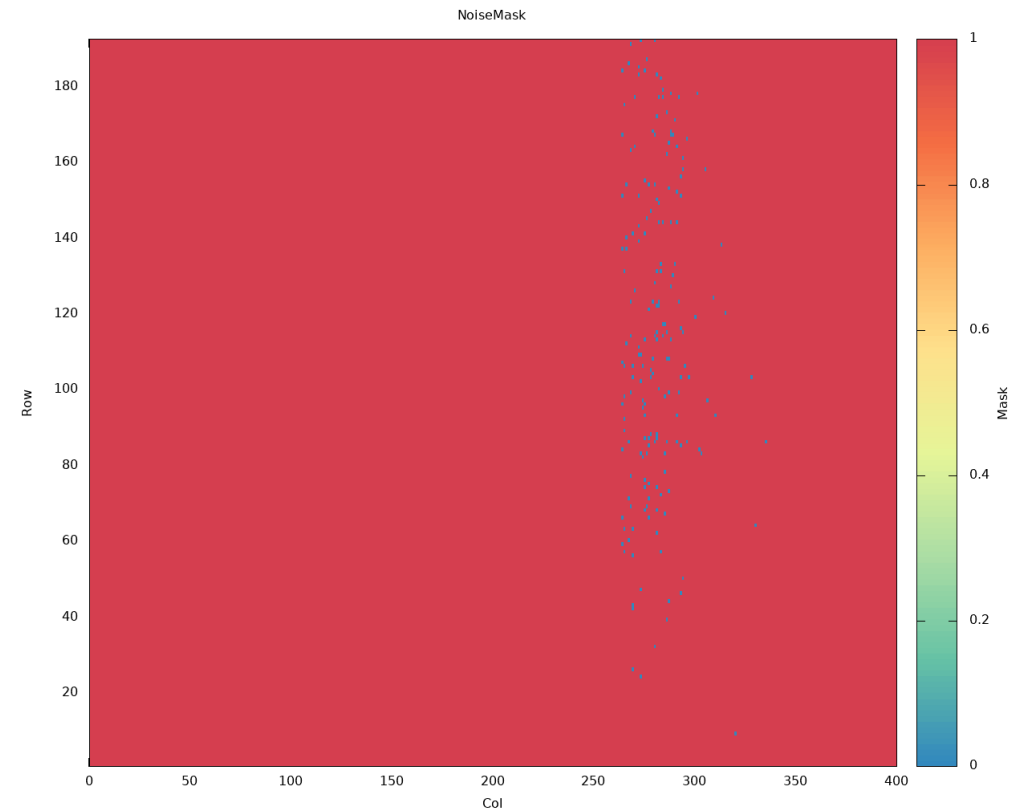
Tuning: noise mask

Very few pixels are masked in the 50x50 while the 25x100 was much noisier probably due to the disconnected pixels.

50x50



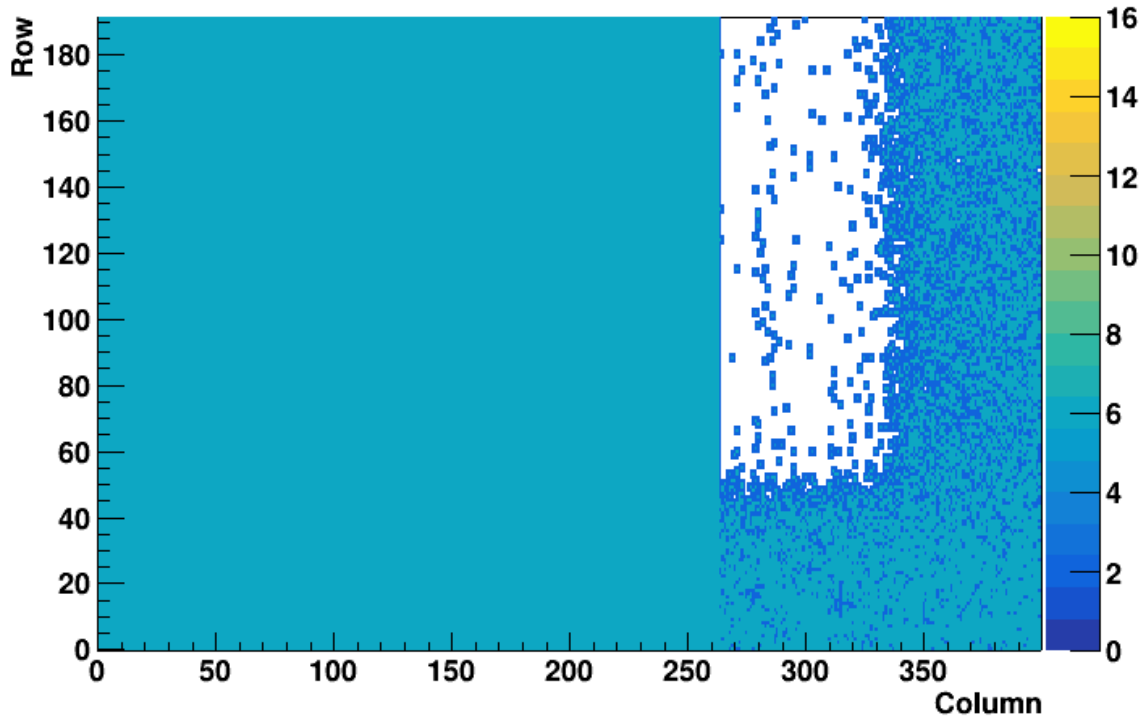
25x100



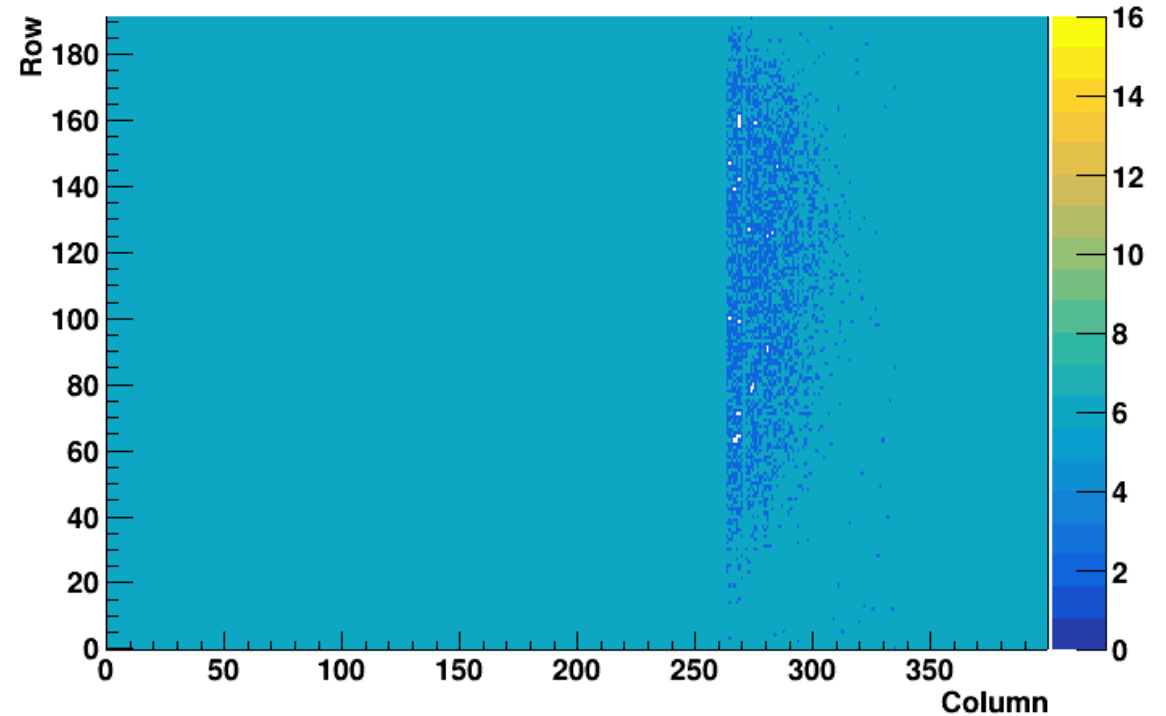
Masked pixel map at 100V

Sensor mask map shows the areas (white areas) where the reconstruction software considerer active for the track reconstruction.

50x50



25x100



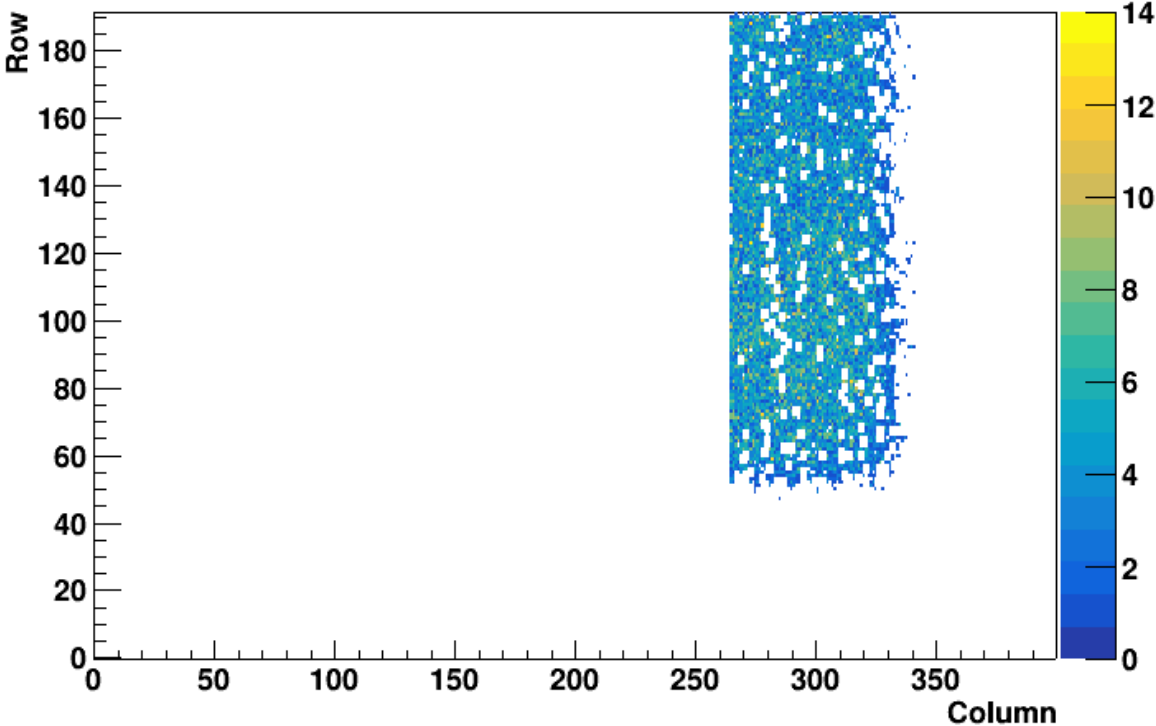
Area of the 25x100 is very small because of a large disconnected area

Full sensor hit map and Efficiency 50x50 at 100V

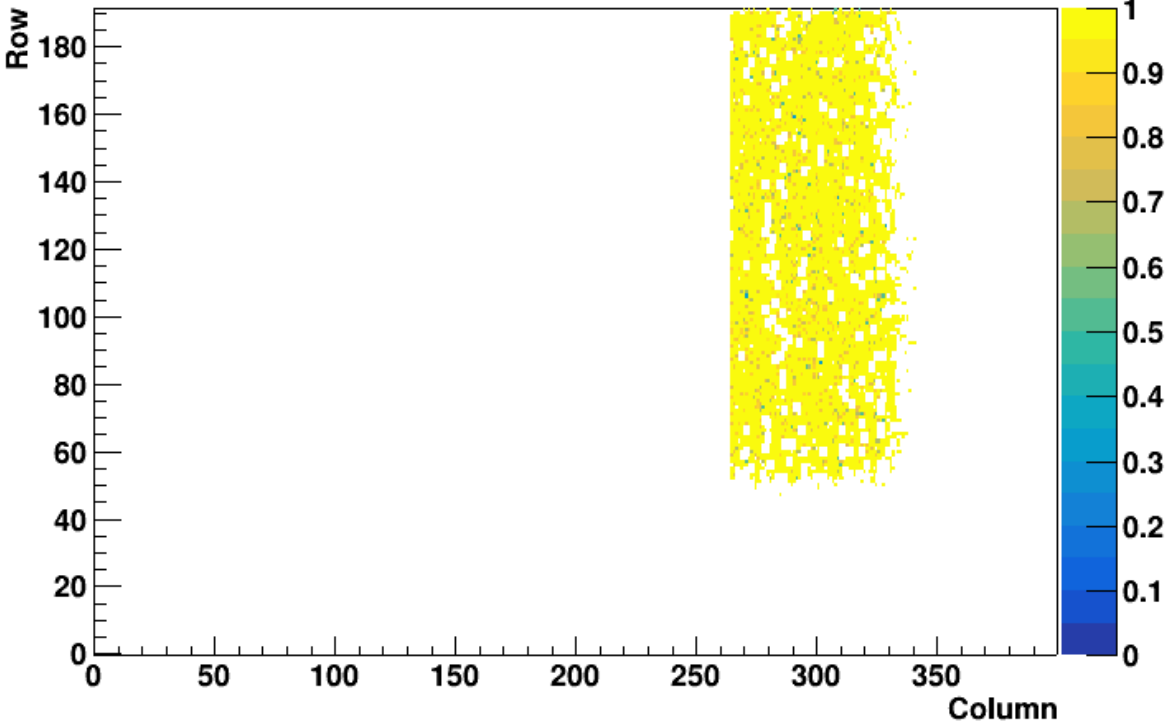
The left plot shows the area where the tracks are reconstructed (trigger window)

On the right plot the efficiency map is shown.

Track Map DUT 118



Efficiency Map DUT 118



KIT, Germany

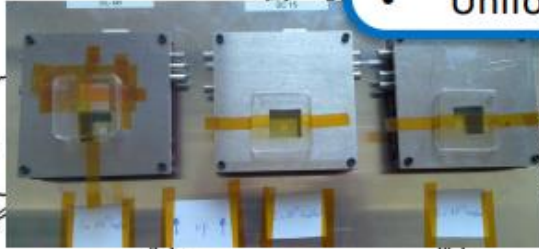


This project has received funding from the European Union's Horizon 2020 Research and Innovation programme under Grant Agreement no. 654268.



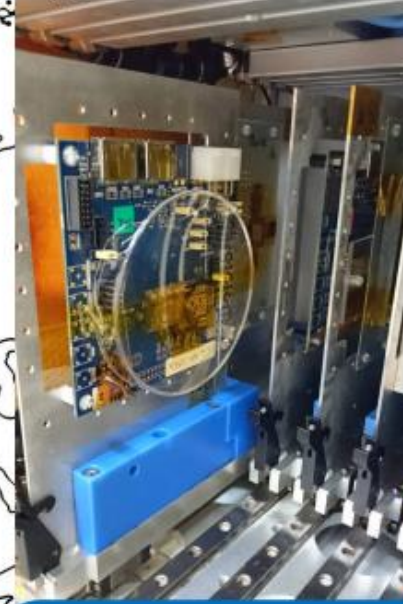
2020

- 23 MeV protons
- Large TID: ~ 750 Mrad for $5e15$ n_{eq}/cm^2
- Uniform irradiation at $T < 0^\circ C$



Birmingham, UK

- 27 MeV (up to 37 MeV) protons
- Large TID: ~ 650 Mrad for $5e15$ n_{eq}/cm^2
- Uniform irradiation at $T < 0^\circ C$



CYRIC, Japan

- 70 MeV protons
- Large TID: ~ 350 Mrad for $5e15$ n_{eq}/cm^2
- Uniform irradiation at $T < 0^\circ C$

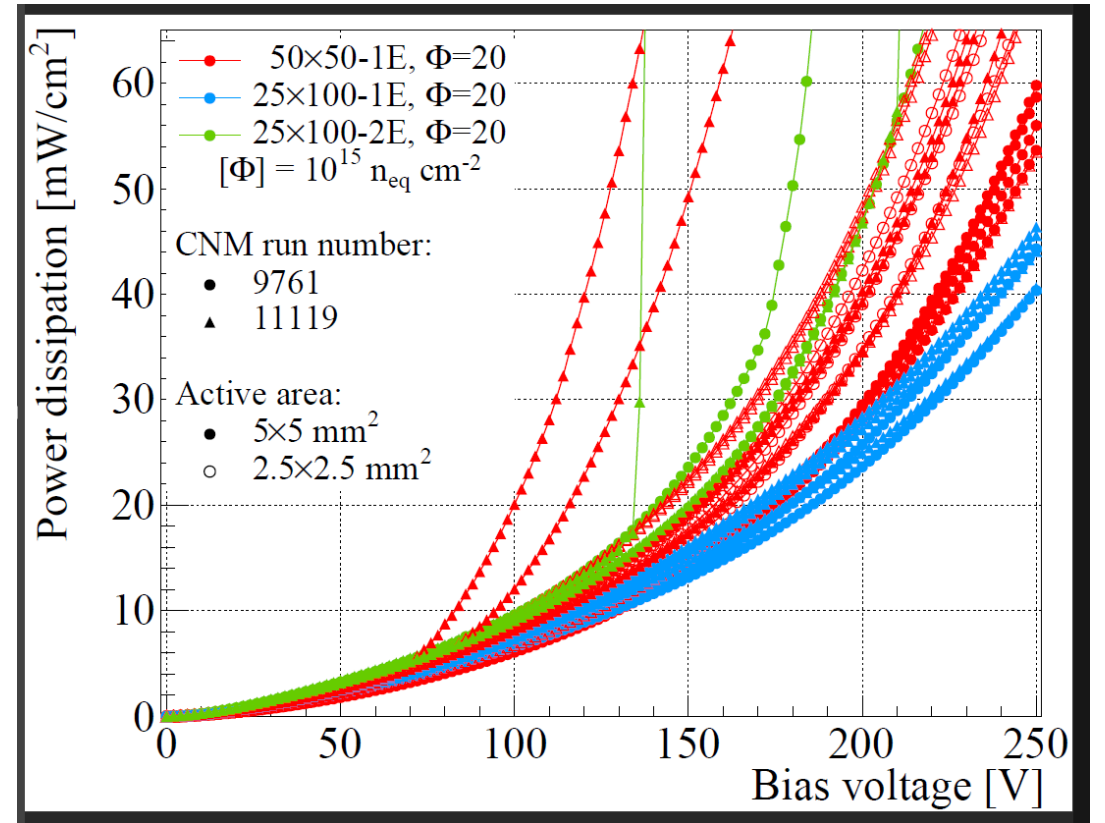
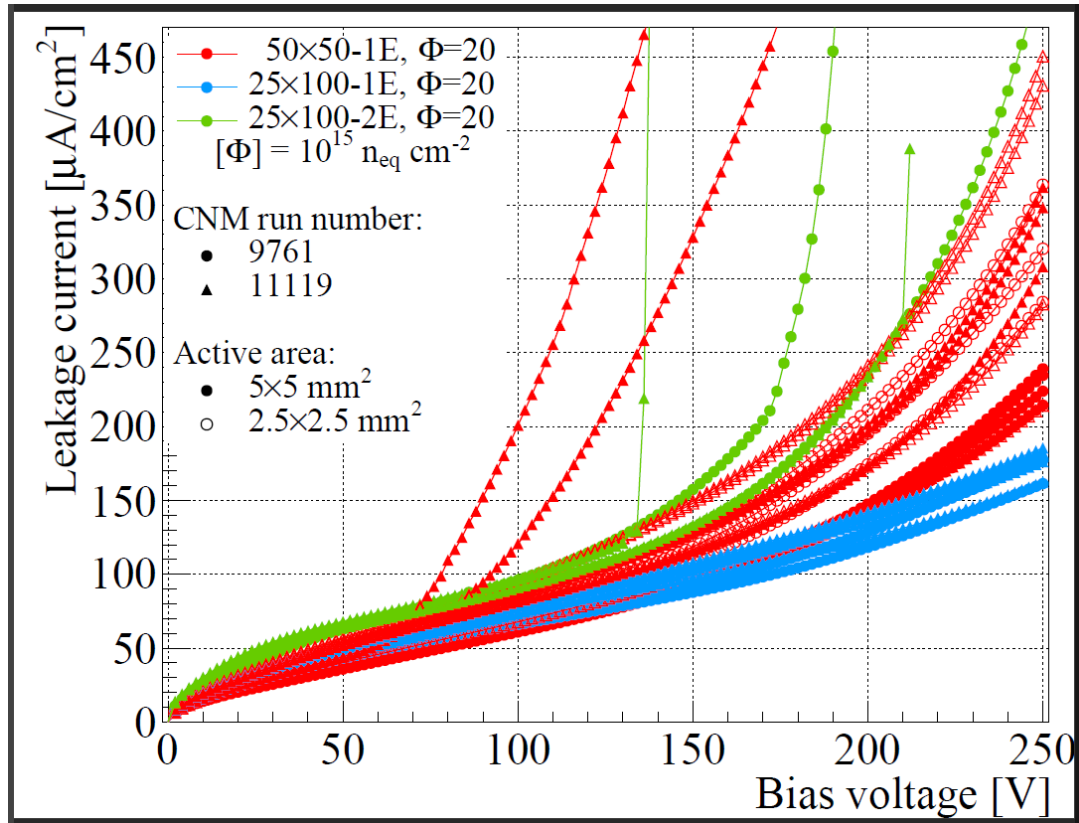
TRIGA reactor at JSI, Slovenia

- Reactor neutrons
- Negligible TID
- Uniform irradiation
- Tantalum in the chip gets activated

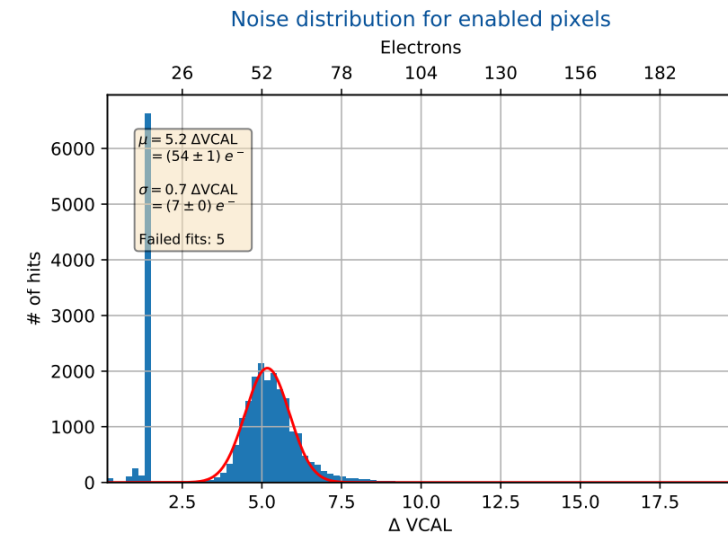
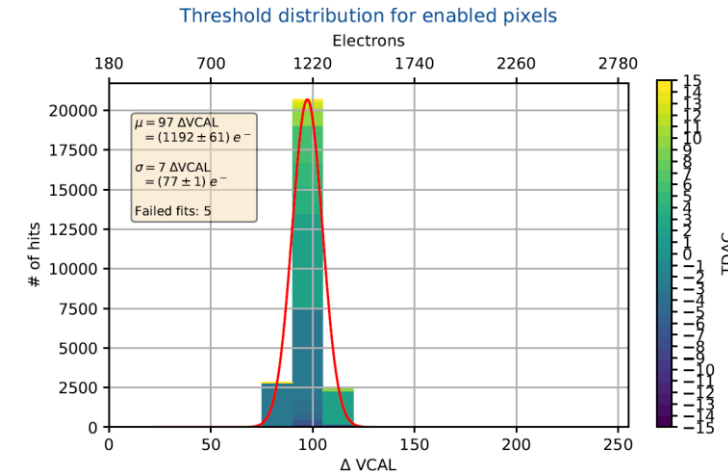
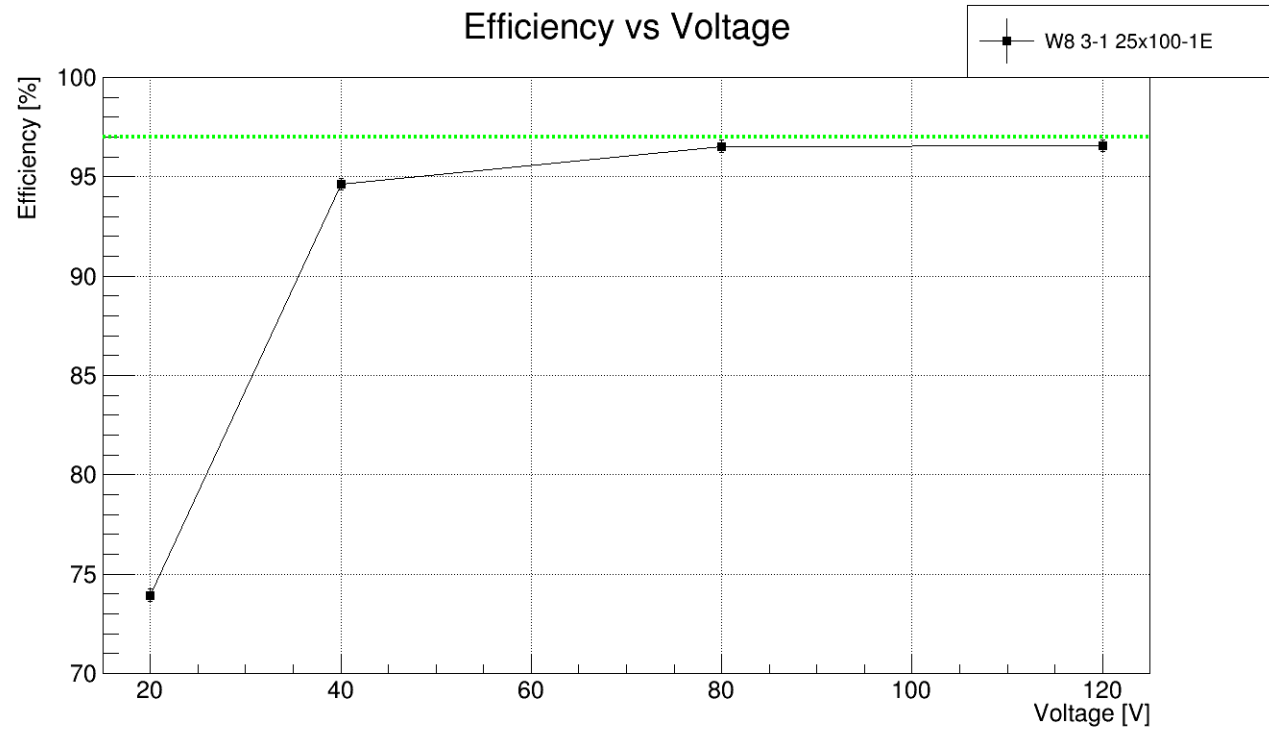


Thanks to: Koji Nakamura, Vladimir Cintro, Laura Gonella & Amelia Hunter, Felix Bögelspacher & Alexander Dierlamm

Diodes IV and Pow



SiSi 25x100-1E irradiated at $1e16$ neq/cm²

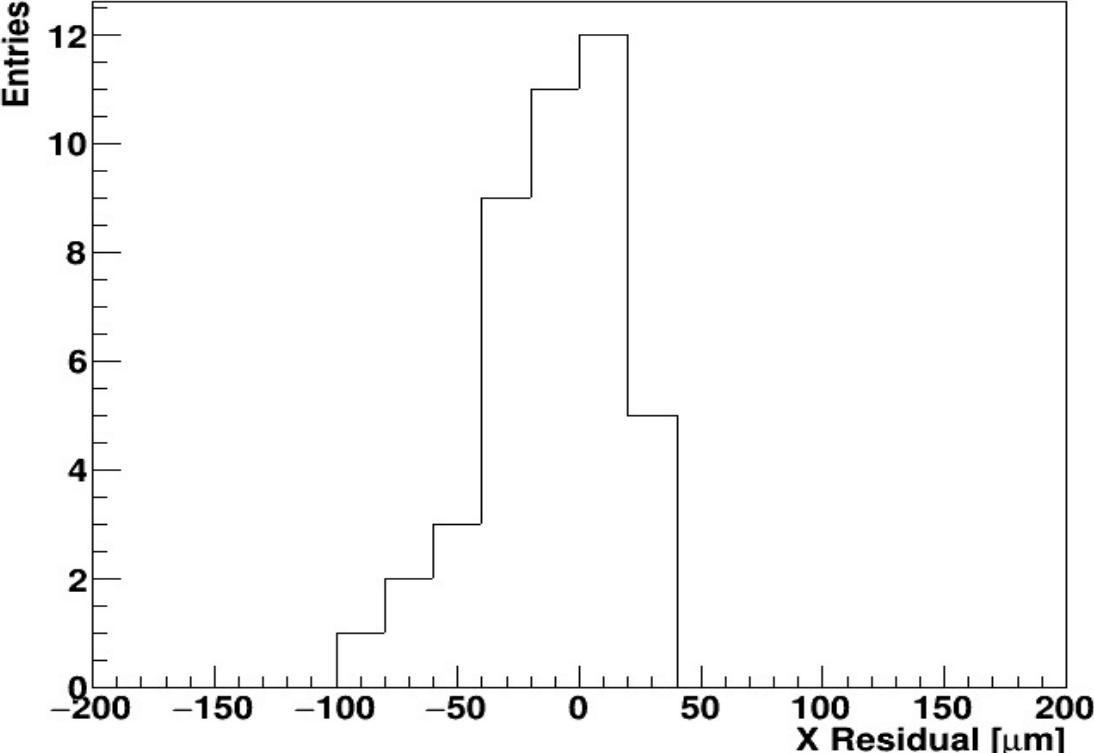


Sensors were uniformly irradiated with a 70MeV proton beams in CYRIC

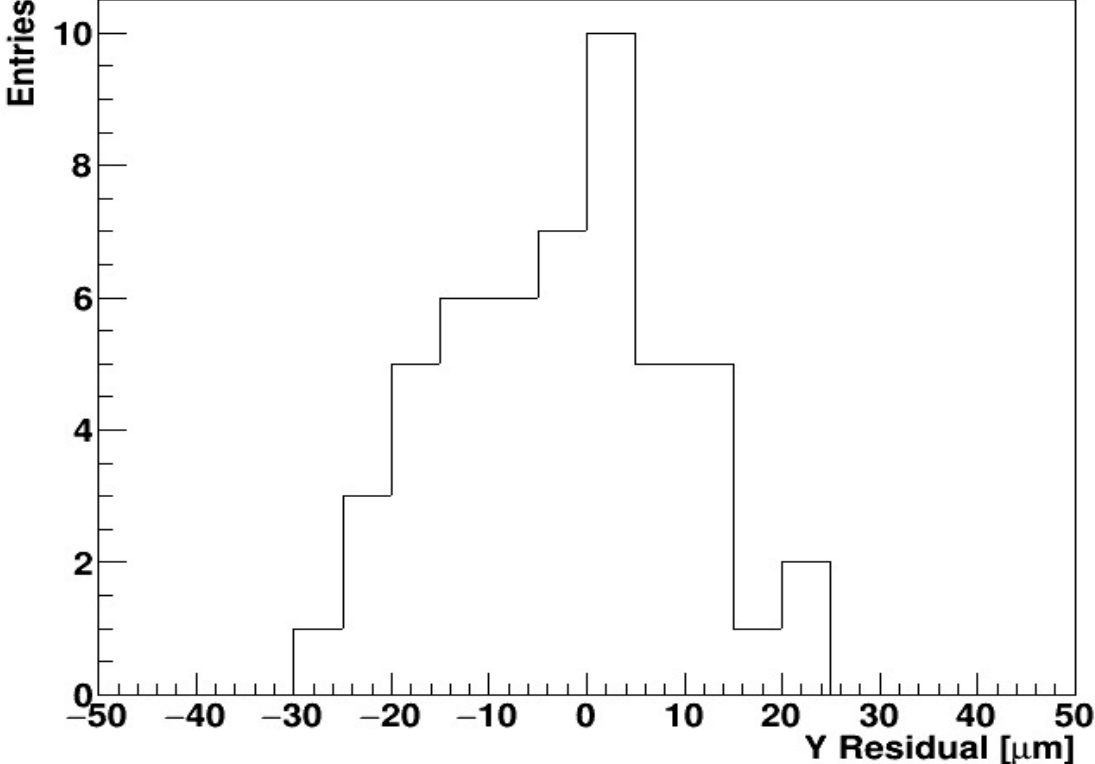
Residual plot 25x100

Residual distributions as expected from the pixel size and the multiple scattering at DESY

X axis



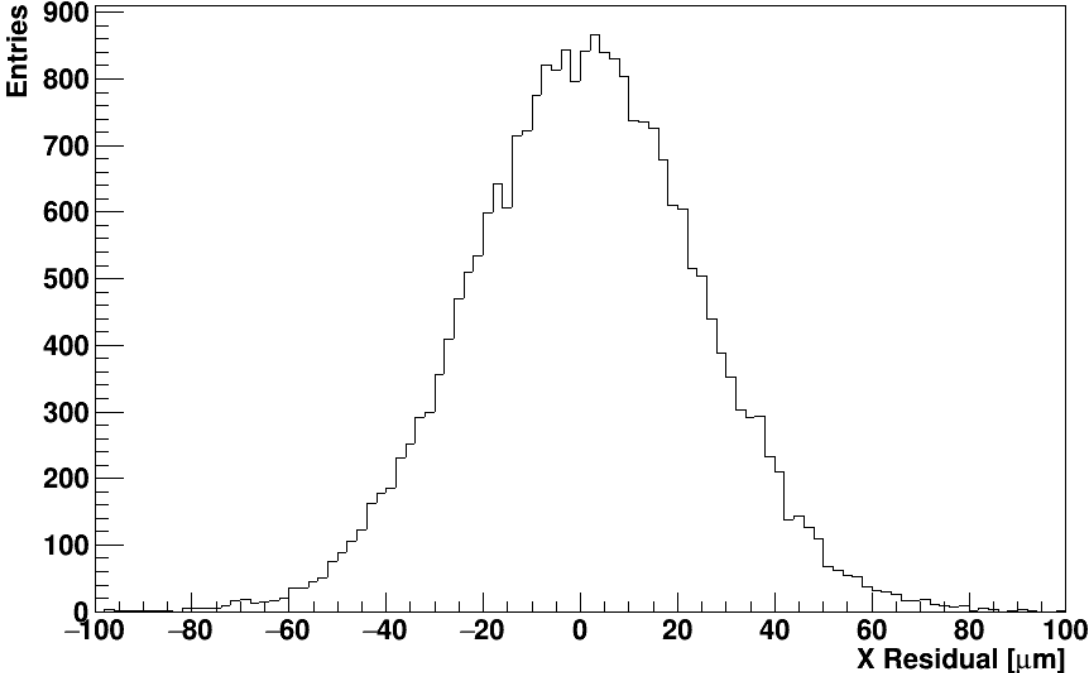
Y axis



Residual plot 50x50

Residual distributions as expected from the pixel size and the multiple scattering at DESY

X axis



Y axis

